

• General Description

The AGM420MBA combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. This device is ideal for load switch and battery protection applications.

• Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

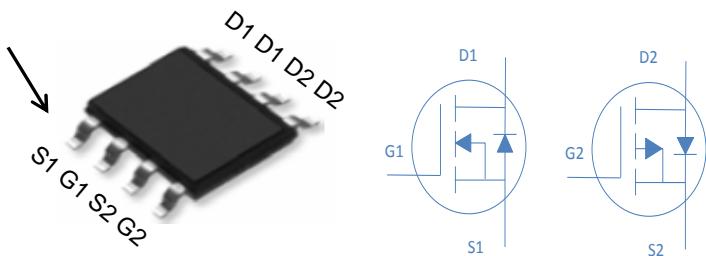
• Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

Product Summary

| BVDSS | RDS _{ON} | ID |
|-------|-------------------|-------|
| 40V | 18mΩ | 7.6A |
| -40V | 40mΩ | -6.8A |

SOP-8 Pin Configuration



Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity |
|----------------|-----------|----------------|-----------|------------|----------|
| AGM420MB | AGM420MBA | SOP8 | 325mm | 16mm | 3000 |

Table 1. Absolute Maximum Ratings ($T_A=25^\circ C$)

| Symbol | Parameter | Rating | | Units |
|-------------|--|------------|------------|-------|
| | | N-Ch | P-Ch | |
| V_{DS} | Drain-Source Voltage ($V_{GS}=0V$) | 40 | -40 | V |
| V_{GS} | Gate-Source Voltage ($V_{DS}=0V$) | ± 20 | ± 20 | V |
| I_D | Drain Current-Continuous($T_c=25^\circ C$) <small>(Note 1)</small> | 7.6 | -6.8 | A |
| | Drain Current-Continuous($T_c=100^\circ C$) | 5.5 | -4.2 | A |
| IDM (pulse) | Drain Current-Continuous@ Current-Pulsed <small>(Note 2)</small> | 24 | -18 | A |
| P_D | Total Power Dissipation($T_c=25^\circ C$) | 2.6 | 2.6 | W |
| | Total Power Dissipation($T_A=100^\circ C$) | 0.7 | 0.7 | W |
| EAS | Avalanche energy <small>(Note 3)</small> | 22 | 18 | mJ |
| TJ,TSTG | Operating Junction and Storage Temperature Range | -55 To 150 | -55 To 150 | °C |

Table 2. Thermal Characteristic

| Symbol | Parameter | Typ | Max | Unit |
|-----------------|---|-----|-----|------|
| $R_{\theta JA}$ | Thermal Resistance Junction-ambient (Steady State) ¹ | --- | 85 | °C/W |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case ¹ | --- | 50 | °C/W |

N-CH Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|--|----------------------------|--|-----|------|----------|------------------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$ | 40 | - | - | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}$ | - | - | 1 | μA |
| Gate-Body Leakage Current | I_{GSS} | $V_{\text{GS}}=\pm 10\text{V}, V_{\text{DS}}=0\text{V}$ | - | - | ± 10 | μA |
| On Characteristics ^(Note 3) | | | | | | |
| Gate Threshold Voltage | $V_{\text{GS}(\text{th})}$ | $V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$ | 1 | 1.8 | 2.5 | V |
| Drain-Source On-State Resistance | $R_{\text{DS}(\text{ON})}$ | $V_{\text{GS}}=10\text{V}, I_{\text{D}}=6\text{A}$ | - | 18 | 24 | $\text{m}\Omega$ |
| | | $V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=5\text{A}$ | - | 24 | 38 | $\text{m}\Omega$ |
| Forward Transconductance | g_{FS} | $V_{\text{DS}}=5\text{V}, I_{\text{D}}=6\text{A}$ | 15 | - | - | S |
| Dynamic Characteristics ^(Note 4) | | | | | | |
| Input Capacitance | C_{iss} | $V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$ | - | 516 | - | PF |
| Output Capacitance | C_{oss} | | - | 82 | - | PF |
| Reverse Transfer Capacitance | C_{rss} | | - | 43 | - | PF |
| Switching Characteristics ^(Note 4) | | | | | | |
| Turn-on Delay Time | $t_{\text{d}(\text{on})}$ | $V_{\text{DD}}=15\text{V}, R_{\text{L}}=2.5\Omega$ $V_{\text{GS}}=10\text{V}, R_{\text{GEN}}=3\Omega$ | - | 4.5 | - | nS |
| Turn-on Rise Time | t_{r} | | - | 2.5 | - | nS |
| Turn-Off Delay Time | $t_{\text{d}(\text{off})}$ | | - | 14.5 | - | nS |
| Turn-Off Fall Time | t_{f} | | - | 3.5 | - | nS |
| Total Gate Charge | Q_{g} | $V_{\text{DS}}=20\text{V}, I_{\text{D}}=6\text{A}, V_{\text{GS}}=10\text{V}$ | - | 8.9 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 2.4 | - | nC |
| Gate-Drain Charge | Q_{gd} | | - | 1.4 | - | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage ^(Note 3) | V_{SD} | $V_{\text{GS}}=0\text{V}, I_{\text{s}}=6\text{A}$ | - | 0.8 | 1.2 | V |

N- Channel Typical Electrical and Thermal Characteristics (Curves)

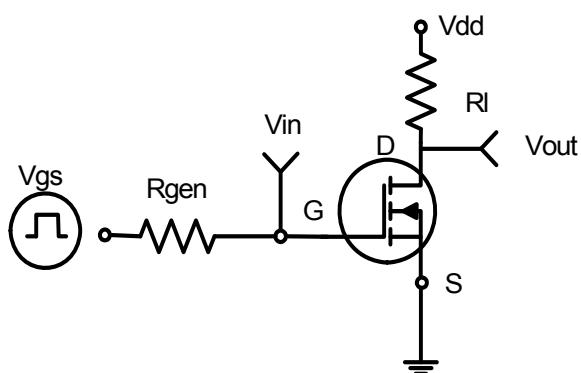


Figure 1:Switching Test Circuit

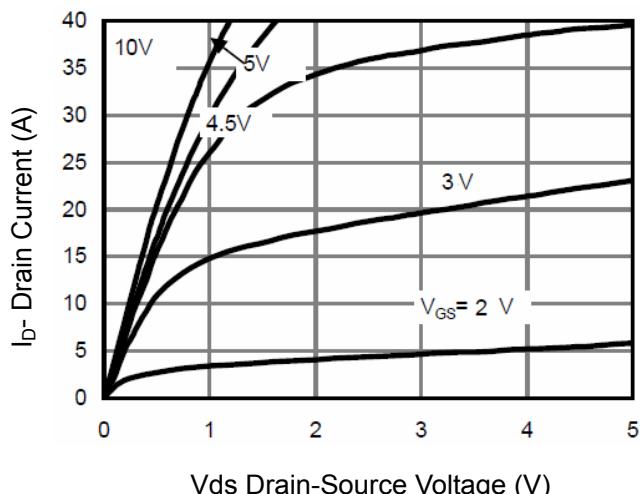


Figure 3 Output Characteristics

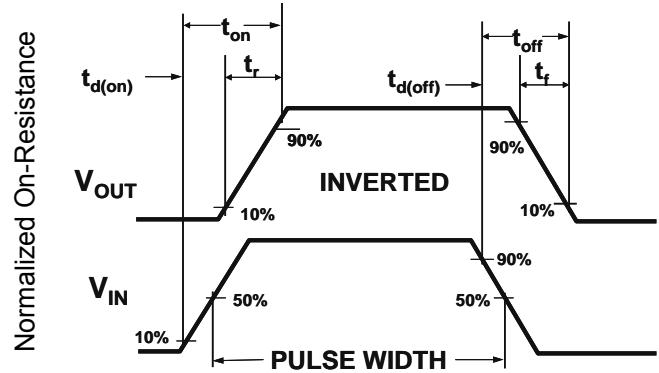


Figure 2:Switching Waveforms

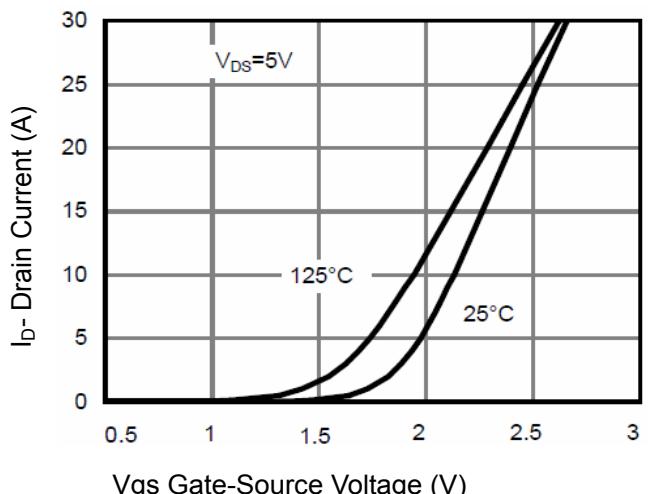


Figure 4 Transfer Characteristics

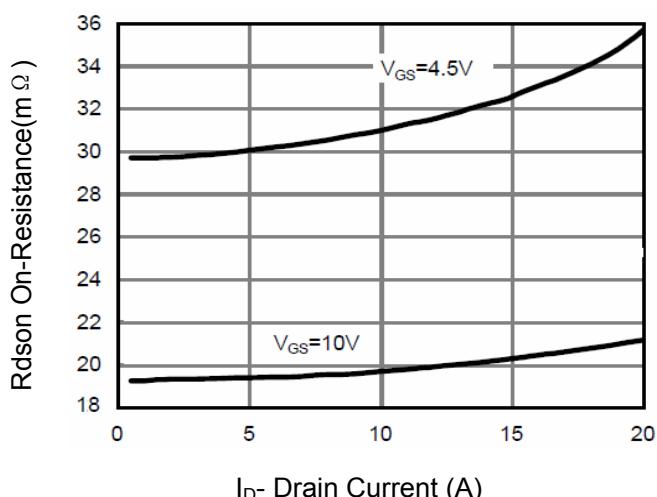


Figure 5 Drain-Source On-Resistance

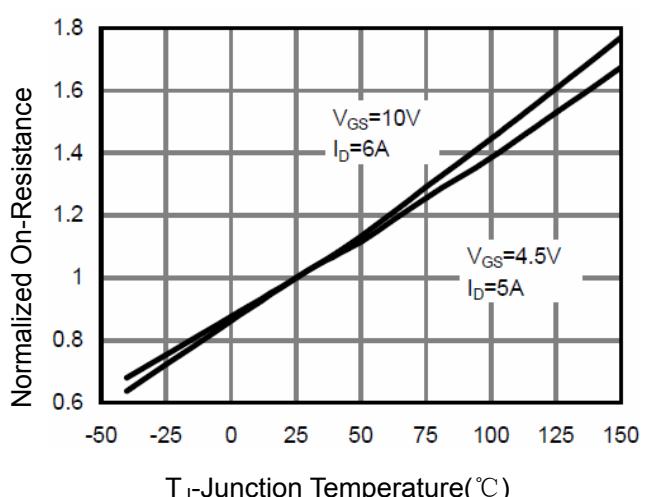


Figure 6 Drain-Source On-Resistance

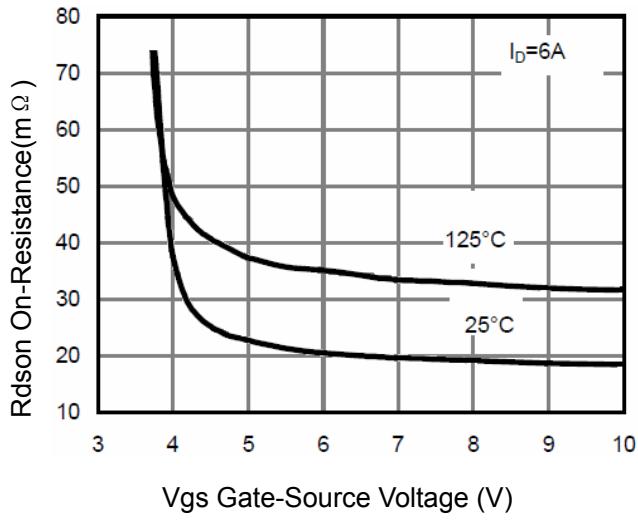


Figure 7 $R_{DS(on)}$ vs V_{GS}

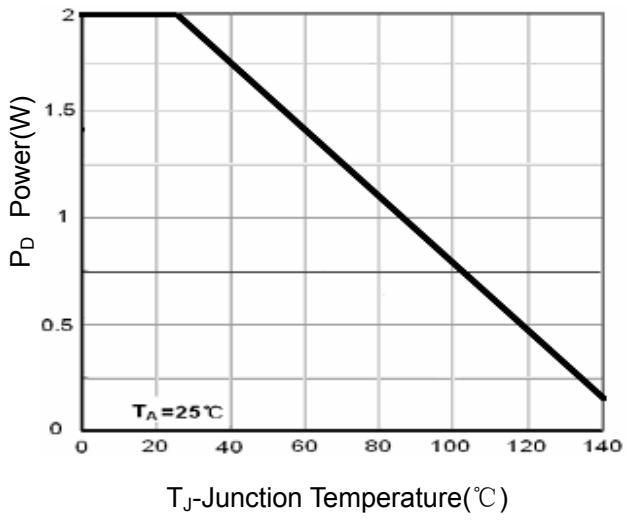


Figure 8 Power Dissipation

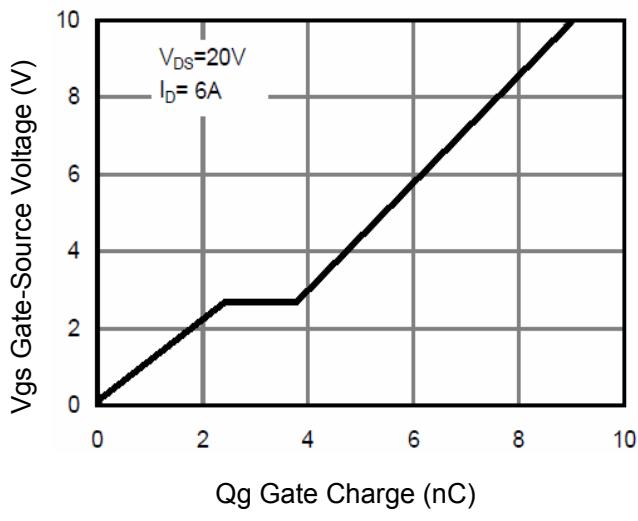


Figure 9 Gate Charge

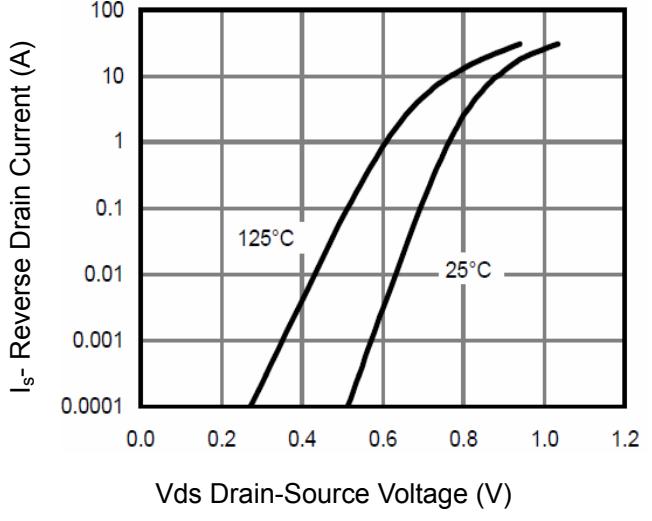


Figure 10 Source-Drain Diode Forward

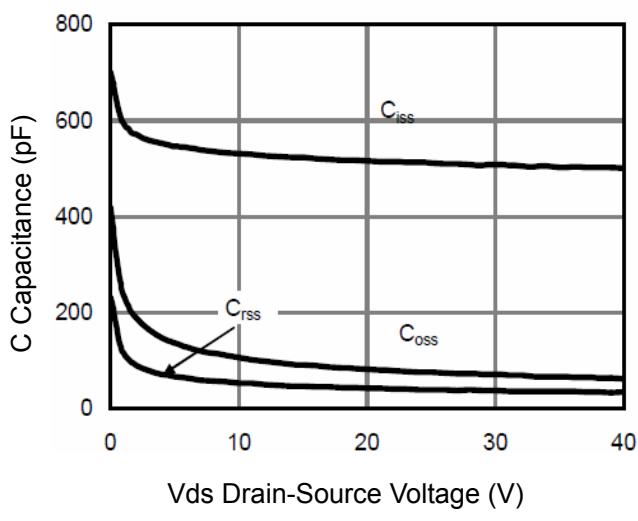


Figure 11 Capacitance vs V_{DS}

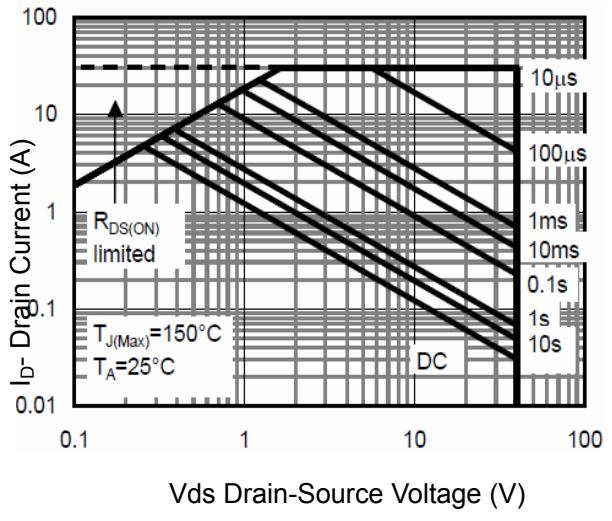


Figure 12 Safe Operation Area

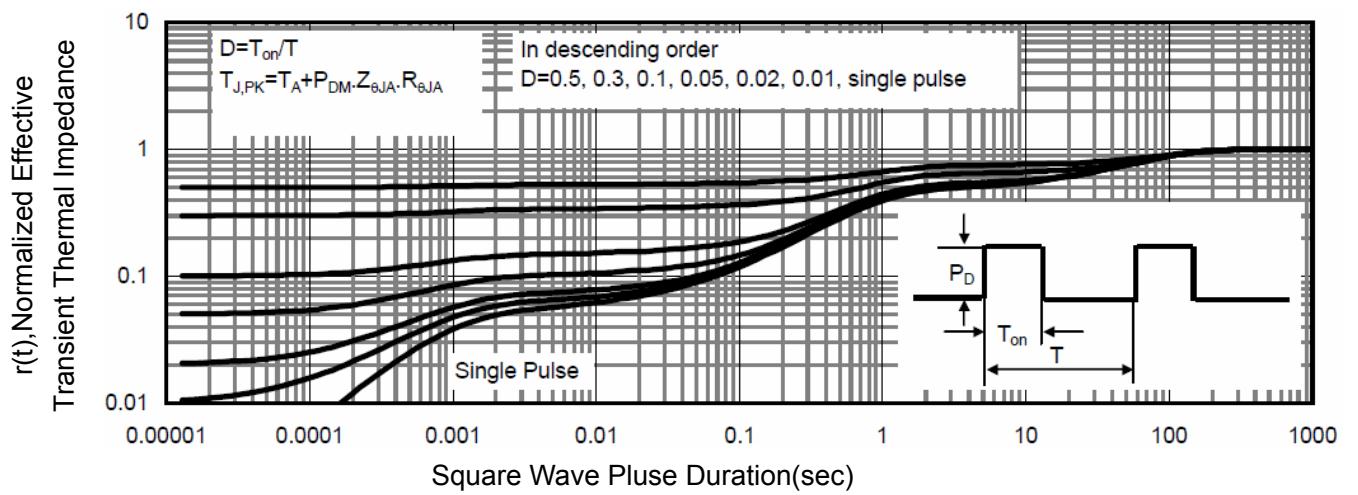


Figure 13 Normalized Maximum Transient Thermal Impedance

•Electronic Characteristics

| Parameter | Symbol | Condition | Min. | Typ | Max. | Unit |
|-----------------------------------|--------------|------------------------------------|------|-----|-----------|-----------|
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS} = 0V, I_D = 250\mu A$ | -40 | | | V |
| Gate Threshold Voltage | $V_{GS(TH)}$ | $V_{GS} = V_{DS}, I_D = -250\mu A$ | -1.1 | 1.7 | -2.5 | V |
| Drain-Source Leakage Current | I_{DSS} | $V_{DS} = -40V, V_{GS} = 0V$ | | | 1.0 | μA |
| Gate- Source Leakage Current | I_{GSS} | $V_{GS} = \pm 20V, V_{DS} = 0V$ | | | ± 100 | nA |
| Static Drain-source On Resistance | $R_{DS(ON)}$ | $V_{GS} = -10V, I_D = -6A$ | | 39 | 58 | $m\Omega$ |
| | | $V_{GS} = -4.5V, I_D = -5A$ | | 61 | 78 | $m\Omega$ |
| Forward Transconductance | g_{FS} | $V_{DS} = -10V, I_D = -5A$ | | 5 | | s |
| Source-drain voltage | V_{SD} | $I_S = -6A$ | | 0.8 | 1.2 | V |

•Electronic Characteristics

| Parameter | Symbol | Condition | Min. | Typ | Max. | Unit |
|------------------------------|-----------|------------|------|-----|------|------|
| Gate Resistance | R_G | $f = 1MHz$ | | | | |
| Input capacitance | C_{iss} | | - | 750 | - | pF |
| Output capacitance | C_{oss} | | - | 105 | - | |
| Reverse transfer capacitance | C_{rss} | | - | 64 | - | |

•Gate Charge characteristics($T_a = 25^\circ C$)

| Parameter | Symbol | Condition | Min. | Typ | Max. | Unit |
|----------------------|----------|---|------|-----|------|------|
| Total gate charge | Q_g | $V_{DD} = -25V$ $I_D = -8A$ $V_{GS} = -10V$ | - | 12 | - | nC |
| Gate - Source charge | Q_{gs} | | - | 2.4 | - | |
| Gate - Drain charge | Q_{gd} | | - | 2.8 | - | |

Note: ① Pulse Test : Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$;

② Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate;

Fig.1 Power Dissipation Derating Curve

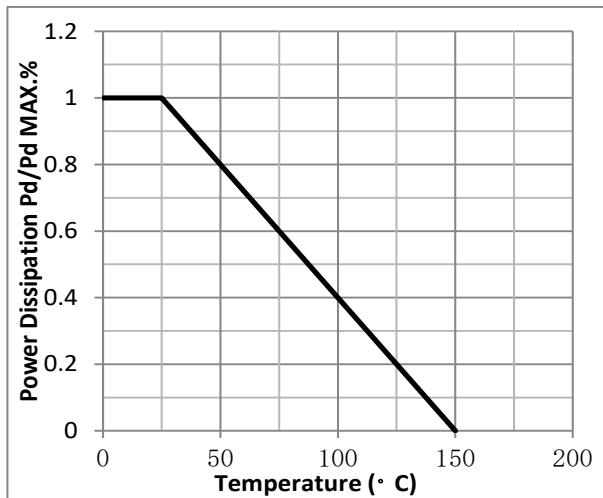


Fig.2 Typical output Characteristics

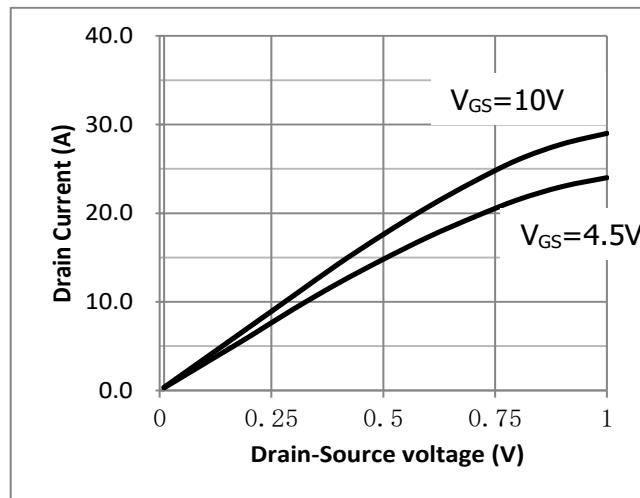


Fig.3 Threshold Voltage V.S Junction Temperature

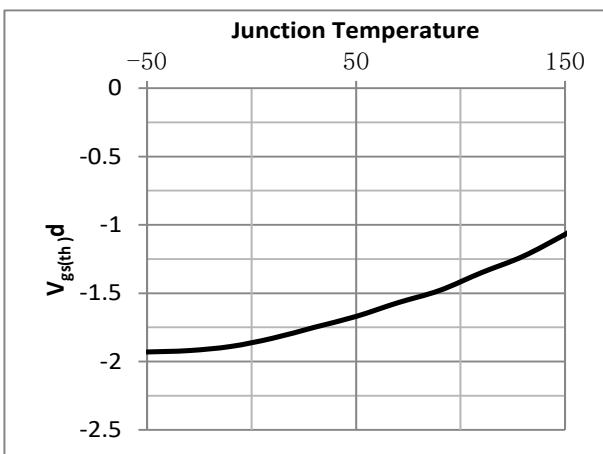


Fig.4 Resistance V.S Drain Current

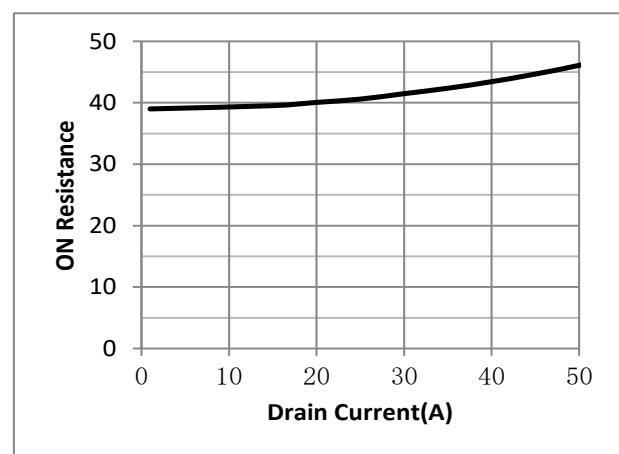


Fig.5 On-Resistance VS Gate Source Voltage

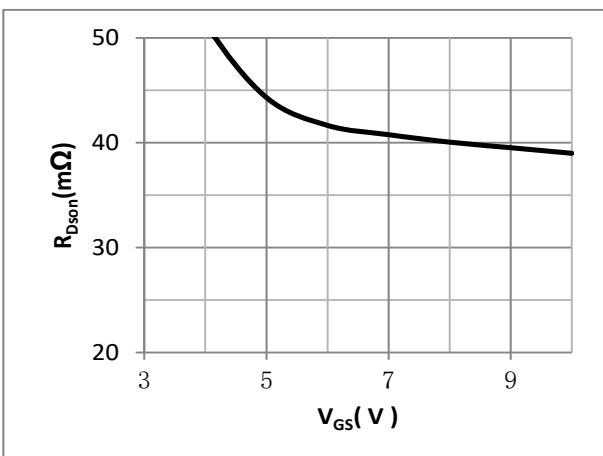


Fig.6 On-Resistance V.S Junction Temperature

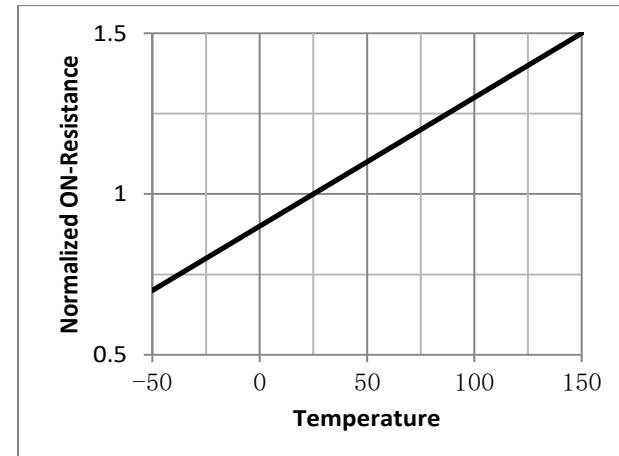


Fig.7 Switching Time Measurement Circuit

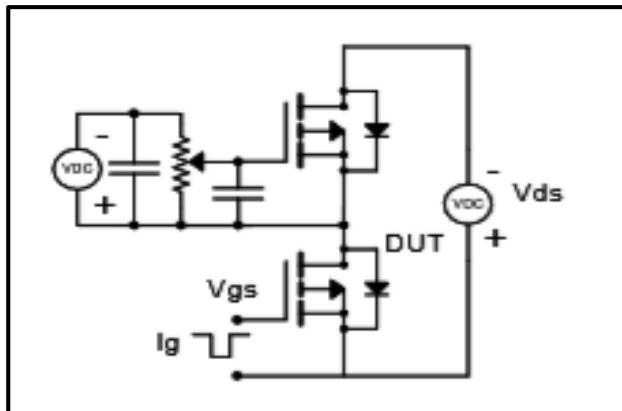


Fig.8 Gate Charge Waveform

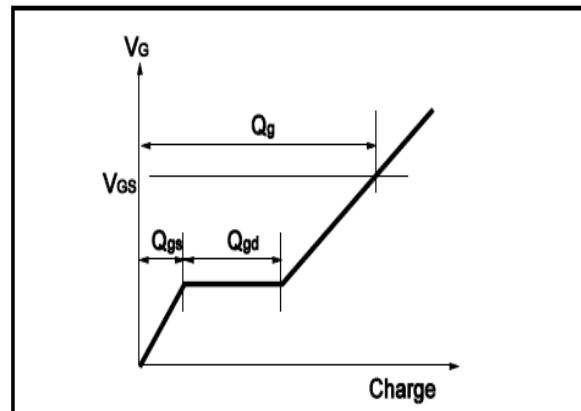


Fig.9 Switching Time Measurement Circuit

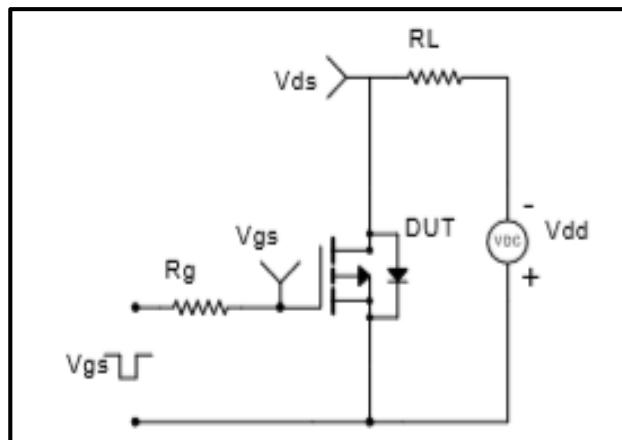


Fig.10 Gate Charge Waveform

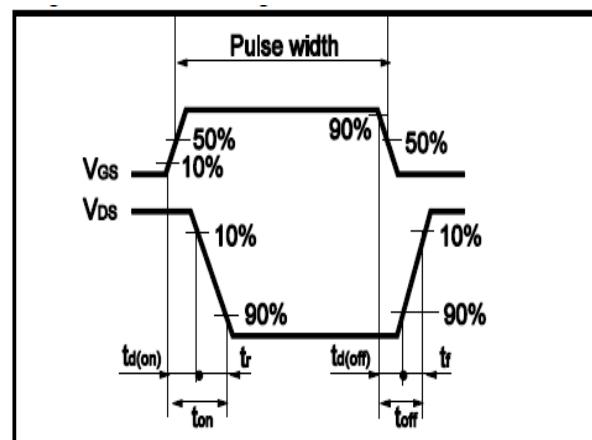


Fig.11 Avalanche Measurement Circuit

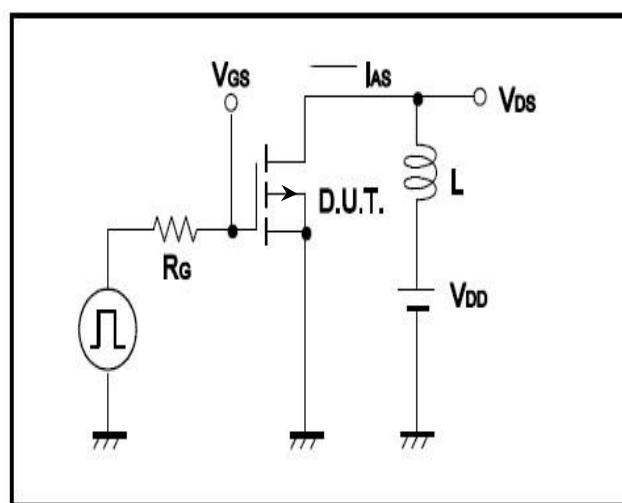
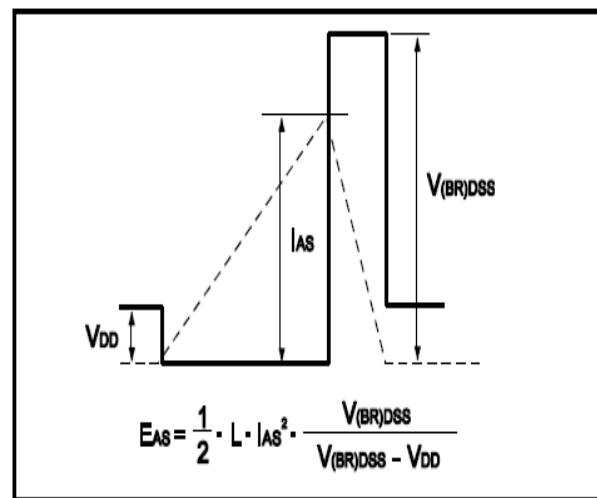
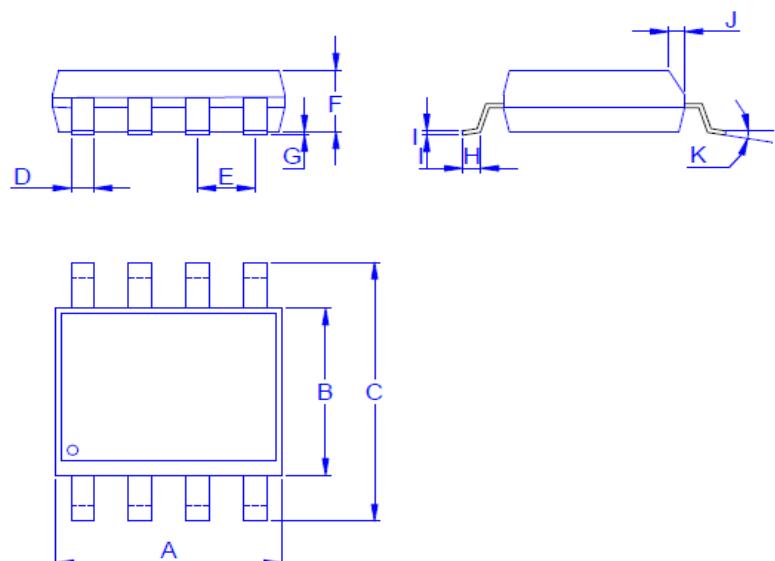


Fig.12 Avalanche Waveform



SOIC-8, 8 leads



Dimension in mm

| Dimension | A | B | C | D | E | F | G | H | I | J | K |
|-----------|------|------|------|------|------|------|------|------|------|------|----|
| Min. | 4.70 | 3.70 | 5.80 | 0.33 | | 1.20 | 0.08 | 0.40 | 0.19 | 0.25 | 0° |
| Typ. | | | | | 1.27 | | | | | | |
| Max. | 5.10 | 4.10 | 6.20 | 0.51 | | 1.62 | 0.28 | 0.83 | 0.26 | 0.50 | 8° |

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